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- UBT™ (Universal Bus Transceiver)
 Combines D-Type Latches and D-Type
 Flip-Flops for Operation in Transparent,
 Latched, Clocked, or Clock-Enabled Mode
- State-of-the-Art Advanced BiCMOS
 Technology (ABT) Widebus™ Design for
 2.5-V and 3.3-V Operation and Low
 Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 2.3-V to 3.6-V V_{CC})
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- High-Drive (-24/24 mA at 2.5-V and -32/64 mA at 3.3-V V_{CC})
- I_{off} and Power-Up 3-State Support Hot Insertion
- Use Bus Hold on Data Inputs in Place of External Pullup/Pulldown Resistors to Prevent the Bus From Floating
- Auto3-State Eliminates Bus Current Loading When Output Exceeds V_{CC} + 0.5 V
- Flow-Through Architecture Facilitates
 Printed Circuit Board Layout
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), Thin Very Small-Outline (DGV) Packages, and 380-mil Fine-Pitch Ceramic Flat (WD) Package

NOTE: For tape and reel order entry:

The DGGR package is abbreviated to GR and the DGVR package is abbreviated to VR.

description

The 'ALVTH16601 devices are 18-bit universal bus transceivers designed for 2.5-V or 3.3-V V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The devices combine D-type latches and D-type flip-flops to allow data flow in transparent, latched, and clocked modes.

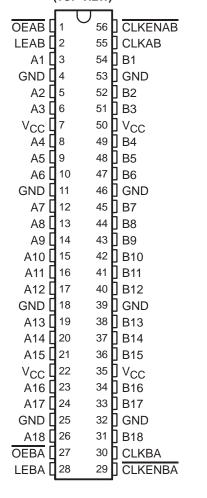


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TEXAS INSTRUMENTS

SN54ALVTH16601 . . . WD PACKAGE SN74ALVTH16601 . . . DGG, DGV, OR DL PACKAGE (TOP VIEW)



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description (continued)

Data flow in each direction is controlled by output-enable (OEAB and OEBA), latch-enable (LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable (CLKENAB and CLKENBA) inputs. For A-to-B data flow, the device operates in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB. Output enable OEAB is active low. When OEAB is low, the outputs are active. When OEAB is high, the outputs are in the high-impedance state.

Data flow for B to A is similar to that of A to B, but uses OEBA, LEBA, CLKBA, and CLKENBA.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

When V_{CC} is between 0 and 1.2 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.2 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN54ALVTH16601 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALVTH16601 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

	OUTPUT				
CLKENAB	OEAB	LEAB	CLKAB	Α	В
Х	Н	Χ	Χ	Χ	Z
Х	L	Н	Χ	L	L
Х	L	Н	Χ	Н	Н
Н	L	L	Χ	X	в ₀ ‡
Н	L	L	Χ	X	в ₀ ‡ в ₀ ‡
L	L	L	\uparrow	L	L
L	L	L	\uparrow	Н	Н
L	L	L	L or H	Χ	в ₀ ‡

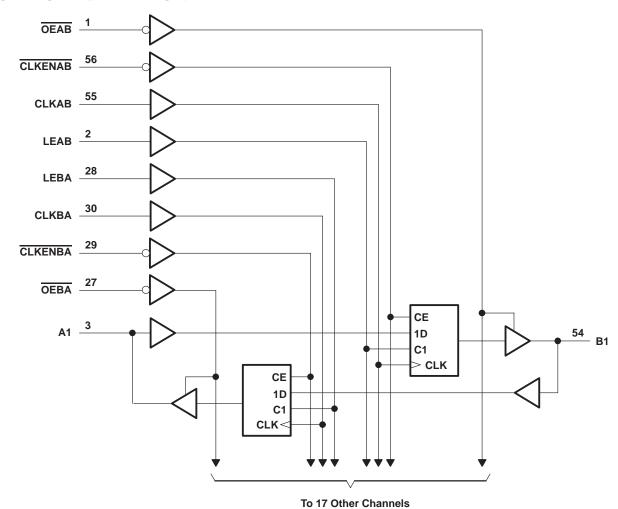
[†] A-to-B data flow is shown: B-to-A flow is similar but uses OEBA, LEBA, CLKBA, and CLKENBA.



[‡] Output level before the indicated steady-state input conditions were established

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logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	-0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V _O (see Note 1)	-0.5 V to 7 V
Output current in the low state, IO: SN54ALVTH16601	96 mA
SN74ALVTH16601	128 mA
Output current in the high state, I _O : SN54ALVTH16601	–48 mA
SN74ALVTH16601	–64 mA
Input clamp current, $I_{ K }(V_1 < 0)$	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DGG package	
DGV package	86°C/W
DL package	74°C/W
Storage temperature range, T _{stq}	-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions, V_{CC} = 2.5 V \pm 0.2 V (see Note 3)

			SN54	ALVTH1	6601	SN74	ALVTH1	6601	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
VCC	Supply voltage	2.3		2.7	2.3		2.7	V	
VIH	High-level input voltage		1.7		2	1.7			V
V _{IL}	Low-level input voltage			Š	0.7			0.7	V
VI	Input voltage		0	Vcc	5.5	0	VCC	5.5	V
loн	High-level output current			7	-6			-8	mA
lai	Low-level output current			2	6			8	mA
lOL	Low-level output current; current duty cycle ≤	50%; f≥1 kHz	20,00	5	18			24	IIIA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q		10			10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200			200			μs/V
T _A	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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recommended operating conditions, $V_{\mbox{\footnotesize{CC}}}$ = 3.3 V \pm 0.3 V (see Note 3)

			SN54	ALVTH1	6601	SN74/	ALVTH1	6601	UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	UNIT
VCC	Supply voltage				3.6	3		3.6	V
VIH	High-level input voltage		2		1/2	2			V
V _{IL}	Low-level input voltage			Ś	0.8			0.8	V
VI	Input voltage		0	VCC	5.5	0	VCC	5.5	V
IOH	High-level output current			1	-24			-32	mA
lai	Low-level output current			2	24			32	mA
lor	Low-level output current; current duty cycle ≤	50%; f≥1 kHz	Q	3	48			64	IIIA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Q		10			10	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200			200			μs/V
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted)

	DAMETED	TEST CO	NUDITIONS	SN54	ALVTH1	6601	SN74	ALVTH1	6601	LINIT
PAI	RAMETER	1531 CC	ONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
VIK		V _{CC} = 2.3 V,	I _I = -18 mA			-1.2			-1.2	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0	.2		VCC-0	.2		
Vон		V _{CC} = 2.3 V	$I_{OH} = -6 \text{ mA}$	1.8						V
		VCC = 2.3 V	$I_{OH} = -8 \text{ mA}$				1.8			
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V},$	$I_{OL} = 100 \mu\text{A}$			0.2			0.2	
			$I_{OL} = 6 \text{ mA}$			0.4				
VOL		V _{CC} = 2.3 V	$I_{OL} = 8 \text{ mA}$						0.4	V
		VCC = 2.3 V	I _{OL} = 18 mA			0.5				
			I _{OL} = 24 mA						0.5	
V _{RST} ‡		V _{CC} = 2.7 V	$I_O = 1 \text{ mA},$ $V_I = V_{CC} \text{ or GND}$			0.55			0.55	V
	Control innuts	V _{CC} = 2.7 V,	$V_I = V_{CC}$ or GND		Š	±1			±1	
	Control inputs	V _{CC} = 0 or 2.7 V,	V _I = 5.5 V		2/4	10			10	
l _l			V _I = 5.5 V		7	10			10	μΑ
	A or B ports	V _{CC} = 2.7 V	$V_I = V_{CC}$		2	1			1	
			V _I = 0		3	-5			– 5	
I _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V	Q					±100	μΑ
I _{BHL} §		$V_{CC} = 2.3 \text{ V},$	V _I = 0.7 V		115			115		μΑ
IBHH		$V_{CC} = 2.3 \text{ V},$	V _I = 1.7 V		-10			-10		μΑ
IBHLO#	ŧ	$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	300			300			μΑ
I _{BHHO}		$V_{CC} = 2.7 \text{ V},$	$V_I = 0$ to V_{CC}	-300			-300			μΑ
lEX☆		$V_{CC} = 2.3 \text{ V},$	V _O = 5.5 V			125			125	μΑ
IOZ(PU	/PD)□	$V_{CC} \le 1.2 \text{ V}, V_O = \frac{0.5}{OE} \text{ V}$ V _I = GND or V _{CC} , \overline{OE} =	to V _{CC} , don't care			±100			±100	μΑ
		V _{CC} = 2.7 V,	Outputs high		0.04	0.1		0.04	0.1	
ICC		$ V_{CC} = 2.7 \text{ V},$ $ O = 0,$	Outputs low		2.5	4.5		2.5	4.5	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.04	0.1		0.04	0.1	
Ci		V _{CC} = 2.5 V,	V _I = 2.5 V or 0		3			3		pF
C _{io}		$V_{CC} = 2.5 \text{ V},$	V _O = 2.5 V or 0		7			7		pF

[†] All typical values are at $V_{CC} = 2.5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[‡] Data must not be loaded into the flip-flops/latches after applying power.

[§] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

The bus-hold circuit can source at least the minimum high sustaining current at VIH min. IBHH should be measured after raising VIN to VCC and then lowering it to VIH min.

[#] An external driver must source at least I_{BHLO} to switch this node from low to high.

An external driver must sink at least IBHHO to switch this node from high to low.

[☆]Current into an output in the high state when V_O > V_{CC}

[□] High-impedance state during power up or power down

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electrical characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted)

D/	ARAMETER	TEST (CONDITIONS	SN54	ALVTH1	6601	SN74	ALVTH1	6601	UNIT
F#	AKAWETEK	lesic	CONDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
٧ıK		$V_{CC} = 3 V$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	$I_{OH} = -100 \mu A$	V _{CC} -0	.2		V _{CC} -0.	.2		
Vон		V _{CC} = 3 V	$I_{OH} = -24 \text{ mA}$	2						V
		VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2			
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V},$	I _{OL} = 100 μA			0.2			0.2	
			$I_{OL} = 16 \text{ mA}$						0.4	
VOL			$I_{OL} = 24 \text{ mA}$			0.5				V
VOL		VCC = 3 V	$I_{OL} = 32 \text{ mA}$						0.5	V
			$I_{OL} = 48 \text{ mA}$			0.55				
			$I_{OL} = 64 \text{ mA}$						0.55	
V _{RST}	‡	V _{CC} = 3.6 V	$I_O = 1 \text{ mA},$ $V_I = V_{CC} \text{ or GND}$		Š	0.55			0.55	V
	Control innuts	V _{CC} = 3.6 V,	V _I = V _{CC} or GND		24	±1			±1	
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V		7	10			10	
II			V _I = 5.5 V		2	10			10	μΑ
	A or B ports	V _{CC} = 3.6 V	$V_I = V_{CC}$		3	1			1	
			V _I = 0	Q		-5			– 5	
l _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V						±100	μΑ
IBHL§		$V_{CC} = 3 V$	V _I = 0.8 V	75			75			μΑ
IBHH		$V_{CC} = 3 V$	V _I = 2 V	-75			-75			μΑ
IBHLO	,#	$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	500			500			μΑ
Івннс	اار	$V_{CC} = 3.6 \text{ V},$	$V_I = 0$ to V_{CC}	-500			-500			μΑ
lEX☆		$V_{CC} = 3 V$	V _O = 5.5 V			125			125	μΑ
I _{OZ(Pl}	U/PD)□	$V_{CC} \le 1.2 \text{ V}, V_{O} = \underline{0.5}$ $V_{I} = \text{GND or } V_{CC}, \overline{\text{OE}}$	V to V _{CC} , = don't care			±100			±100	μΑ
		V _{CC} = 3.6 V,	Outputs high		0.06	0.1		0.06	0.1	
ICC		$I_{O}=0$,	Outputs low		3.5	5		3.5	5	mA
		$V_I = V_{CC}$ or GND	Outputs disabled		0.06	0.1		0.06	0.1	
∆ICC◊		$V_{CC} = 3 \text{ V to } 3.6 \text{ V, On}$ Other inputs at V_{CC} or	e input at V _{CC} – 0.6 V, GND			0.4			0.4	mA
Ci		$V_{CC} = 3.3 \text{ V},$	V _I = 3.3 V or 0		3			3		pF
C _{io}		V _{CC} = 3.3 V,	V _O = 3.3 V or 0		7			7		pF
		•								

 $[\]uparrow$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



[‡] Data must not be loaded into the flip-flops/latches after applying power.

[§] The bus-hold circuit can sink at least the minimum low sustaining current at V_{IL} max. I_{BHL} should be measured after lowering V_{IN} to GND and then raising it to V_{IL} max.

The bus-hold circuit can source at least the minimum high sustaining current at V_{IH} min. I_{BHH} should be measured after raising V_{IN} to V_{CC} and then lowering it to V_{IH} min.

[#] An external driver must source at least IBHLO to switch this node from low to high.

An external driver must sink at least IBHHO to switch this node from high to low.

 $[\]star$ Current into an output in the high state when $V_O > V_{CC}$

[□] High-impedance state during power up or power down

[♦] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

				SN54ALVTI	H16601	SN74ALVT	H16601	UNIT
				MIN	MAX	MIN	MAX	UNII
fclock	Clock frequency				150		150	MHz
	Pulse duration	LE high		1.8		1.8		20
t _W	Pulse duration	CLK high or low		2.3		2.3		ns
	A or B before CLK		Data high	4		4		
			Data low	5.2		5.2		
١.	Setup time	A or B before LE↓	CLK high	0.7	EN	0.7		
t _{su}			CLK low	0.9	14	0.9		ns
1			Data high	1.7,0		1.7		
		CLKEN before CLK↑	Data low	2.3		2.3		
		A B - 4 O K^	Data high	0.5		0.5		
		A or B after CLK↑	Data low	0.5		0.5		
		A an D affan I E l	CLK high	2.3		2.3		
th	Hold time	A or B after LE↓	CLK low	2.4		2.4		ns
		OLICEN - (1 OLIC	Data high	0.5		0.5		
		CLKEN after CLK↑	Data low	0.5		0.5		

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 2)

				SN54ALVT	H16601	SN74ALVT	H16601	UNIT
				MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency				150		150	MHz
	Dulas direction	LE high		1.8		1.8		
t _W	Pulse duration	CLK high or low		2.3		2.3		ns
		A or B before CLK↑		2.4		2.4		
				3.8		3.8		
١.	Catua tima	A or B before LE↓	CLK high	1	EN	1		
t _{su}	Setup time		CLK low	0.6	Ty.	0.6		ns
			Data high	1.4,0		1.4		
		CLKEN before CLK↑	Data low	1.9		1.9		
		A B (1 OL 1/4)	Data high	0.5		0.5		
		A or B after CLK↑	Data low	0.5		0.5		
1.	Hald time	A B 6 151		2		2		
^t h	Hold time	A or B after LE↓	CLK low	2.3		2.3		ns
		OLIVEN - fra - OLIV	Data high	0.6		0.6		
		CLKEN after CLK↑	Data low	0.5		0.5		

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switching characteristics over recommended operating free-air temperature range, C_L = 30 pF, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

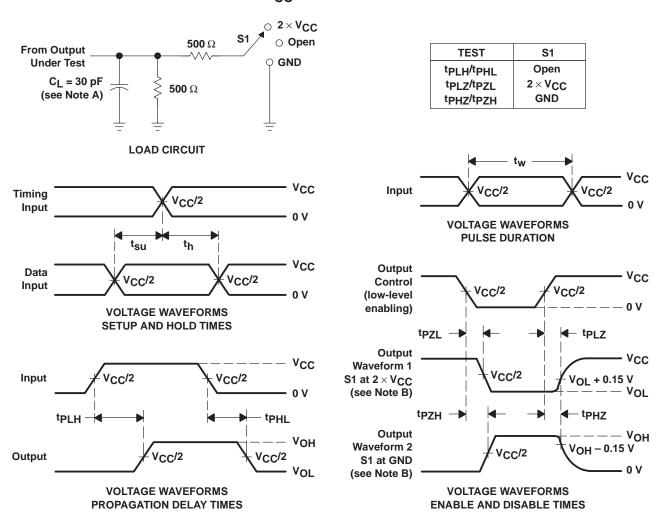
PARAMETER	FROM	то	SN54ALV	ГН16601	SN74ALVT	H16601	UNIT
PARAMETER	PARAMETER (INPUT)		MIN	MAX	MIN	MAX	UNIT
fmax			150		150		MHz
t _{PLH}	B or A	A or B	1.1	<u>4</u> .1	1.1	4.1	ns
t _{PHL}	D OI A	AOID	1.6	4.8	1.6	4.8	115
^t PLH	LEBA or LEAB	A or B	2.1	5	2.1	5	ns
^t PHL	LEDA OI LEAD	AOID	2.4	5.4	2.4	5.4	115
^t PLH	CLKBA or CLKAB	A or B	2	5	2	5	ns
t _{PHL}	CLNBA OI CLNAB	AOIB	2.5	5.9	2.5	5.9	115
^t PZH	OEBA or OEAB	A or B	1.2	4.8	1.2	4.8	ns
t _{PZL}	OEBA OF OEAB	AUID	1	4.6	1	4.6	115
^t PHZ	OEBA or OEAB	A or B	1.2	5.2	1.2	5.2	ns
tPLZ	OEBA OI OEAB	AOID	1	3.9	1	3.9	113

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	то	SN54ALV	TH16601	SN74ALVT	H16601	UNIT	
PARAMETER	(INPUT) (OUTPUT)		MIN	MAX	MIN	MAX	UNIT	
f _{max}			150		150		MHz	
t _{PLH}	D A	A or B	1.4	3 .9	1.4	3.9	no	
t _{PHL}	B or A	AUID	1.1	3.9	1.1	3.9	ns	
t _{PLH}	LEBA or LEAB	A or B	2	4.6	2	4.6	ns	
t _{PHL}	LEBA OF LEAB	AUID	2.1	4.6	2.1	4.6	115	
^t PLH	CLKBA or CLKAB	A or B	1.9	4.5	1.9	4.5	ns	
^t PHL	CLNDA OI CLNAD	AOID	2.2	4.6	2.2	4.6	115	
^t PZH	OEBA or OEAB	A or B	Q 1	4.2	1	4.2	ns	
t _{PZL}	OEBA OF OEAB	AUID	1	4.4	1	4.4	115	
^t PHZ	OEBA or OEAB	A or B	1.8	5.3	1.8	5.3	ne	
t _{PLZ}	OEDA OF OEAB	AUID	1.7	4.6	1.7	4.6	ns	

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PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 V \pm 0.2 V$



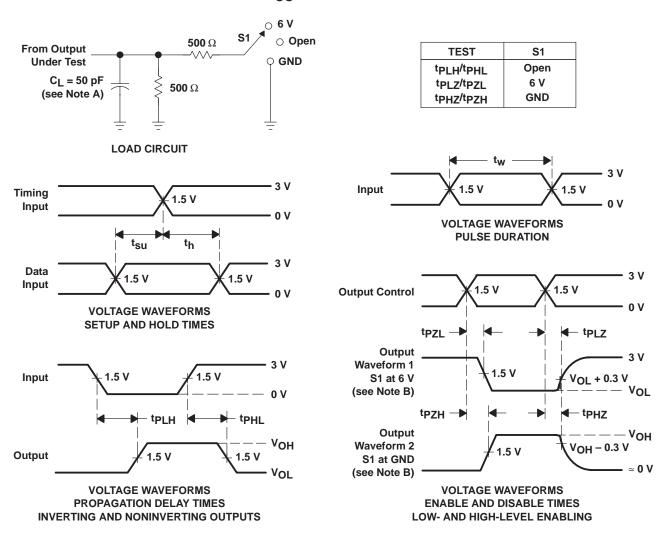
NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform22 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50~\Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms





com 5-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVTH16601GRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVTH16601VRE4	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH16601DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH16601DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH16601GR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVTH16601VR	ACTIVE	TVSOP	DGV	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

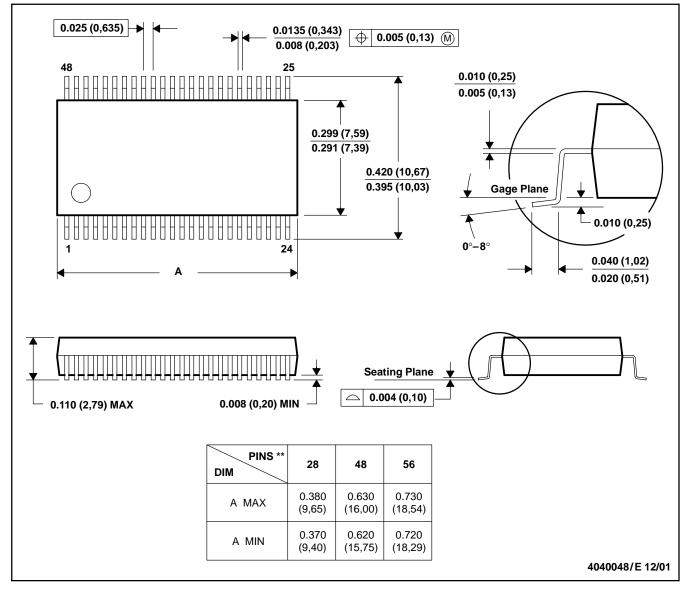
D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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